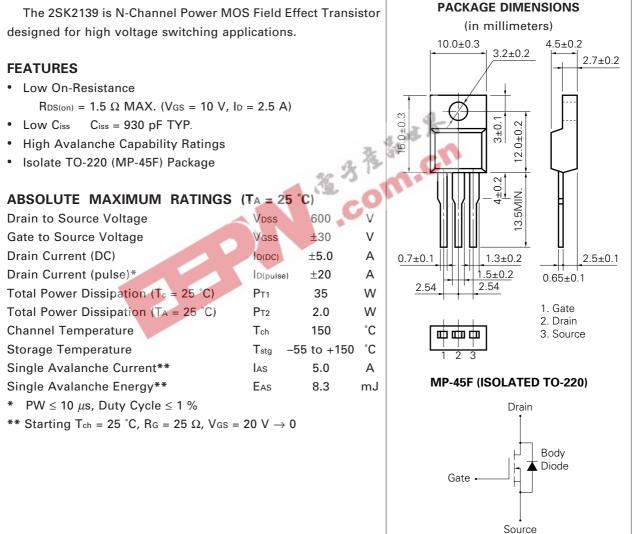
DATA SHEET



MOS FIELD EFFECT TRANSISTOR **2SK2139**

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

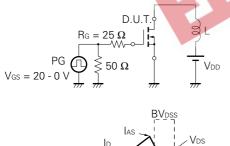
DESCRIPTION



| ELECTRICAL | CHARACTERISTICS | (T _A = 25 °C) |
|------------|-----------------|--------------------------|
|------------|-----------------|--------------------------|

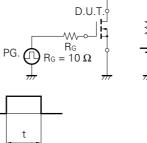
| CHARACTERISTIC | SYMBOL | MIN. | TYP. | MAX. | UNIT | TEST CONDITIONS |
|-------------------------------------|-----------------|----------|-------------|------|------|---|
| Drain to Source On-state Resistance | RDS(on) | | 1.1 | 1.5 | Ω | V_{GS} = 10 V, I_{D} = 2.5 A |
| Gate to Source Cutoff Voltage | $V_{GS(off)}$ | 2.5 | | 3.5 | V | $V_{DS} = 10 V, I_{D} = 1 mA$ |
| Forward Transfer Admittance | y _{fs} | 1.5 | | | S | $V_{DS} = 10 V, I_{D} = 2.5 A$ |
| Drain Leakage Current | Ioss | | | 100 | μΑ | $V_{DS} = 600 V, V_{GS} = 0$ |
| Gate to Source Leakage Current | lgss | | | ±100 | nA | $V_{GS} = \pm 30 \text{ V}, \text{ V}_{DS} = 0$ |
| Input Capacitance | Ciss | | 930 | | pF | $V_{DS} = 10 V$ |
| Output Capacitance | Coss | | 200 | | pF | $V_{GS} = 0$ |
| Reverse Transfer Capacitance | Crss | | 40 | | pF | f = 1 MHz |
| Turn-On Delay Time | td(on) | | 20 | | ns | $V_{GS} = 10 V$ |
| Rise Time | tr | | 10 | | ns | $V_{DD} = 150 V$ |
| Turn-Off Delay Time | td(off) | | 60 | | ns | I_{D} = 2.5 A, R_{G} = 10 Ω |
| Fall Time | tr | | 12 | | ns | $R_L = 60 \ \Omega$ |
| Total Gate Charge | QG | | 30 | | nC | $V_{GS} = 10 V$ |
| Gate to Source Charge | Q _{GS} | | 6.0 | | nC | ID = 5.0 V |
| Gate to Drain Charge | Qgd | | 15 | 13 | nC | VDD = 450 V |
| Diode Forward Voltage | VF(S-D) | | 1.0 | 2 | V | IF = 5.0 A, Vgs = 0 |
| Reverse Recovery Time | trr | | 3 20 | 00 | ns | IF = 5.0 A |
| Reverse Recovery Charge | Qrr | \sim . | 1.4 | | μC | di/dt = 50 A/ μ s |

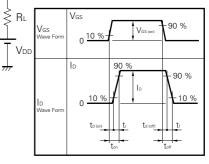
Test Circuit 1 Avalanche Capability



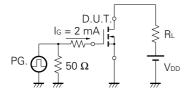


Test Circuit 2 Switching Time





Test Circuit 3 Gate Charge



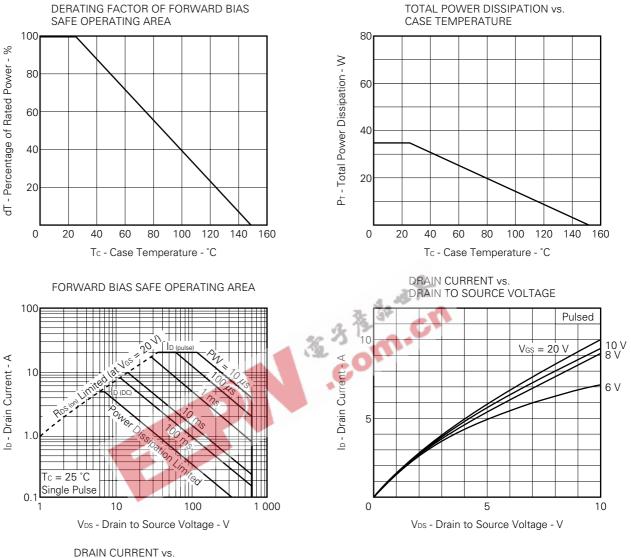
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

Vgs

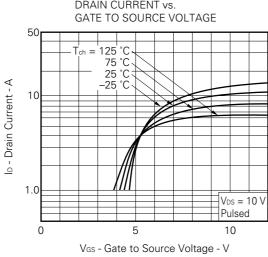
t = 1us

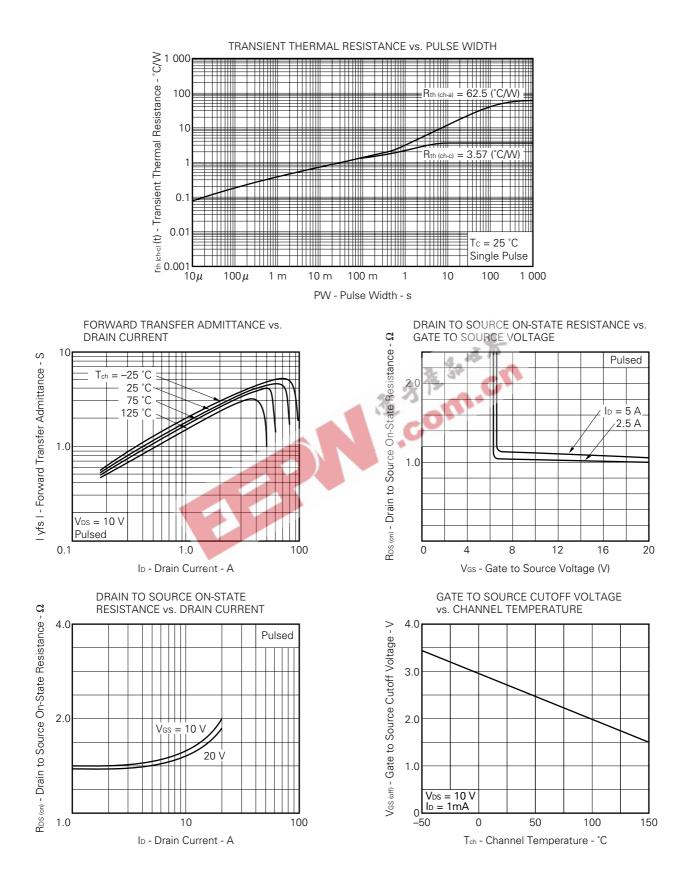
Duty Cycle \leq 1 %

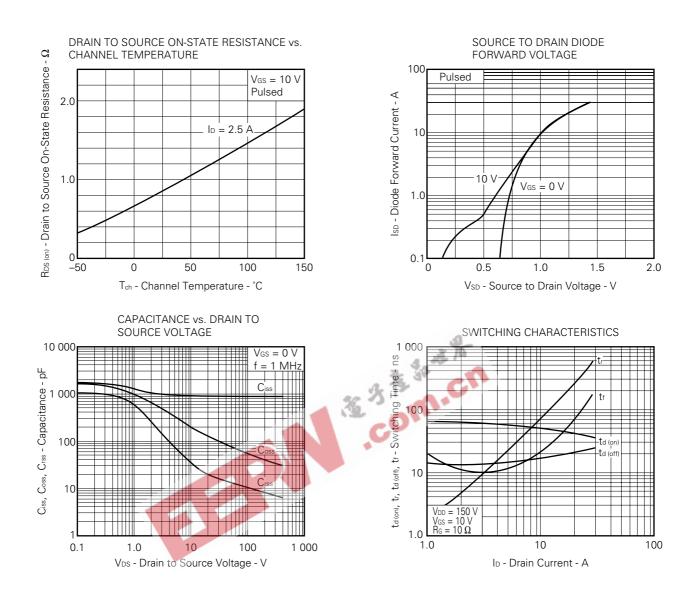
0.

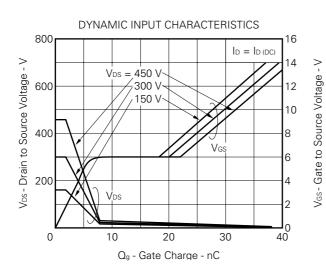


TYPICAL CHARACTERISTICS (TA = 25 °C)





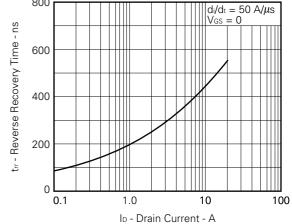




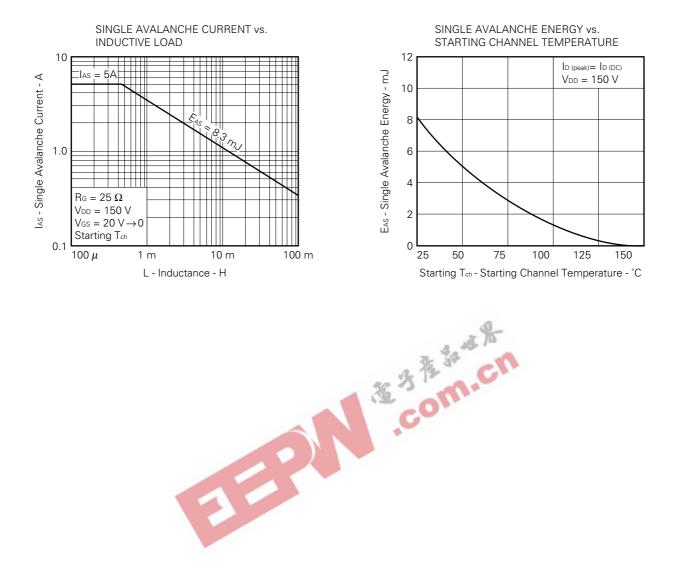
NEC

REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

800



5



NEC

REFERENCE

| Document Name | Document No. |
|--|--------------|
| NEC semiconductor device reliability/quality control system. | TEI-1202 |
| Quality grade on NEC semiconductor devices. | IEI-1209 |
| Semiconductor device mounting technology manual. | IEI-1207 |
| Semiconductor device package manual. | IEI-1213 |
| Guide to quality assurance for semiconductor devices. | MEI-1202 |
| Semiconductor selection guide. | MF-1134 |
| Power MOS FET features and application switching power supply. | TEA-1034 |
| Application circuits using Power MOS FET. | TEA-1035 |
| Safe operating area of Power MOS FET. | TEA-1037 |

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device is actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.



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Anti-radioactive design is not implemented in this product.

M4 94.11